HKPCA
Hong Kong Printed Circuit Association
香港綫路板協會

通告
MEMO

敬请关注

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致 To	:	全體會員 All Members	編號 No.	:	M-23-XX
由 From	:	香港綫路板協會 HKPCA	日期 Date	:	xx-01-2023

IC 基板 SAP FCBGA 整體解決方案
IC Substrate SAP Total Solution For FCBGA

日期 Date	2023 年 2 月 23 日（星期四） 23 Feb., 2023 (Thur.)
時間 Time	14:30-16:00
形式 Format	綫上研討會-騰訊會議 Online Webinar- VooV Meeting
語言 Language	普通話 Putonghua
費用 Fee:	免費 – HKPCA 會員報名優先 FREE – HKPCA members will be given priority for registration.
查詢 Enquiry	深圳秘書處 Shenzhen Secretariat Office: 袁小姐 Ms Susan Yuan: (86) 755 8624 1673; training@hkpca.org
研討會內容 Seminar Content	1. FCBGA Market & Application; FCBGA 市場及應用; 2. FCBGA Design Trend and Challenge; FCBGA 設計趨勢與挑戰; 3. Fine Line Solution on Metallization for IC Substrate IC 載板的金屬化細線解決方案
研討會對象 Target Audience	從事 PCB 生產、技術及管理等工作相關的人員 PCB Manufacturing personnel involve in production, technology and management
講師簡介 Speaker Biography	江寧，浙江大學物理學博士，復旦大學博士後。自 2005 年開始，先後在在聖戈班，陶氏化學和杜邦從事技術開發，市場開發和投資，先後擔任過研發經理，亞太區投資經理和全球戰略客戶總監，目前在杜邦電子互聯科技業務擔任市場及業務開發總監，負責 IC 載板市場和相關業務拓展。在陶氏和杜邦工作 12 年中，江博士一直專注于電子材料領域的新技術投資與新業務開發 Leon Jiang graduated from Zhejiang University with Ph.D. in Physics, and had a Post-Doctor in Fudan University. Since 2005, Leon worked in Saint-Gobain, Dow Chemical and DuPont for technology development, market development and corporate investment, has served as R&D Manager, Corporate Venture Manager and Corporate Account Executive. Currently, Leon is the Market & Business Development Leader for Interconnect Solutions Business in DuPont, responsible for the business development of IC substrate materials and solutions. During his 12 years' career in Dow & DuPont, Leon focused on new technical investment and new business development especially in electronic materials.

	汤绍夏，臺灣輔仁大學化學博士 。現任職陶氏/杜邦金屬化電鍍產品行銷和新專案管理。曾於 Phoenix Precision Technology（基板製造商）公司担任工藝工程及研發，曾任英特爾客戶負責人。 Tang, Sao-Hsia graduated from Fu Jen University with PhD in Chemistry. Currently, he is responsible for metallized electroplating product marketing and new project management in Dow/Dupont. He also worked as R&D/Process Engineering at Phoenix Precision Technology (substrate manufacturer) and was responsible for Intel account.
報名截止日期 Deadline	**2023 年 2 月 22 日（星期三） / 22 Feb., 2023 (Wed.)**